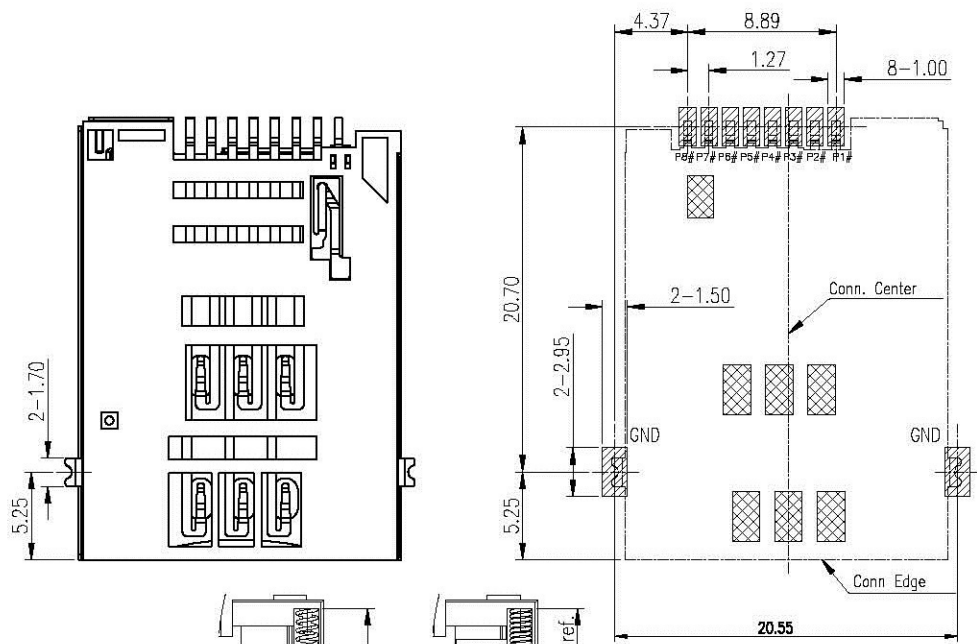
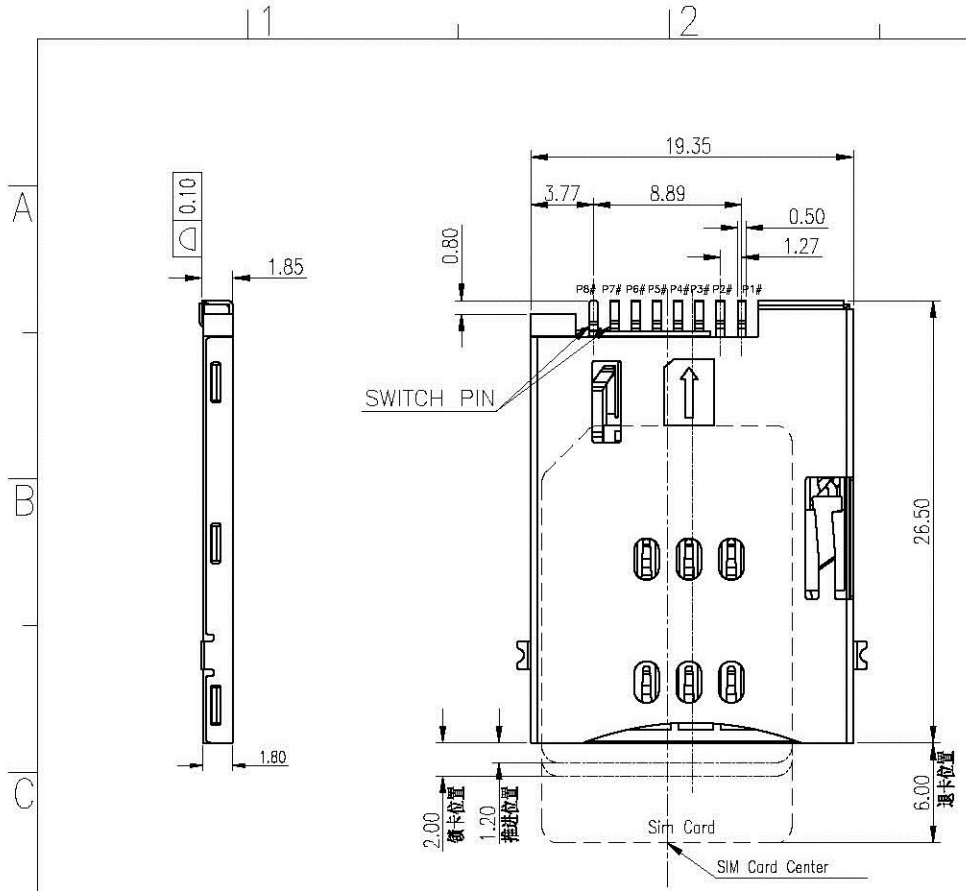
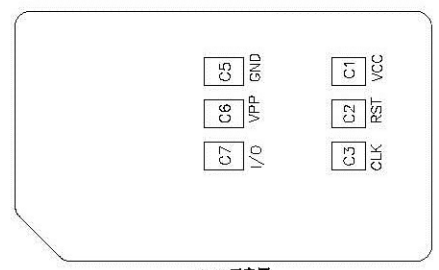
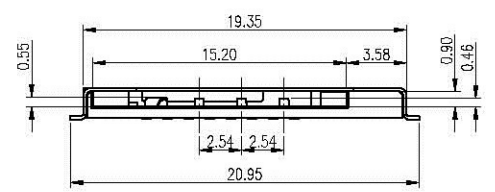
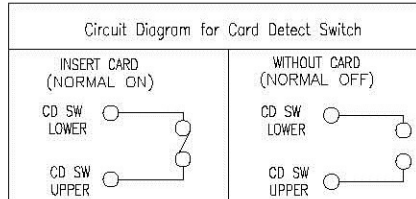
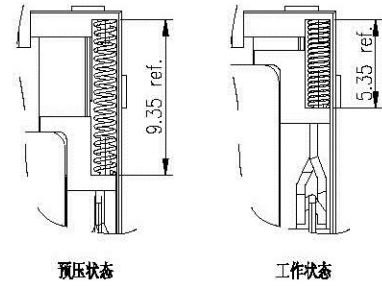


REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	2016.03.09			



RECOMMENDED PCB LAYOUT(TOP VIEW)
 GENERAL TOLERANCES:±0.05

NOTES:
 1)MATERIAL:
 HOUSING: LCP UL 94V-0
 CONTACT: C5210R-H,T=0.15
 SHELL: SUS304,T=0.20
 MYLAR: POLYESTER
 2)FINISH:
 CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED 50u*Min. NICKEL
 SHELL: 30u*Min. NICKEL UNDERPLATED OVERALL,
 GOLD FLASH PLATED ON SOLDER TAILS
 3.INFRARED REFLOW SOLDERING: 10sec. Min. at 260^{±10}



SIM 示意图
 芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

MILLIMETERS	INCH	UNITS
X° ± 2°	X° ± 2°	MM
.X ± 0.30	.XX ± 0.012	MAT'L
.XX ± 0.20	.XXX ± 0.008	SEE NOTES
.XXX ± 0.10	.XXXX ± 0.004	FINISH
		SEE NOTES
		QTY
		SEE NOTES

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深圳市连欣科技有限公司

PART NUMBER: 102011322

APPD: Sean

CHKD: Yang

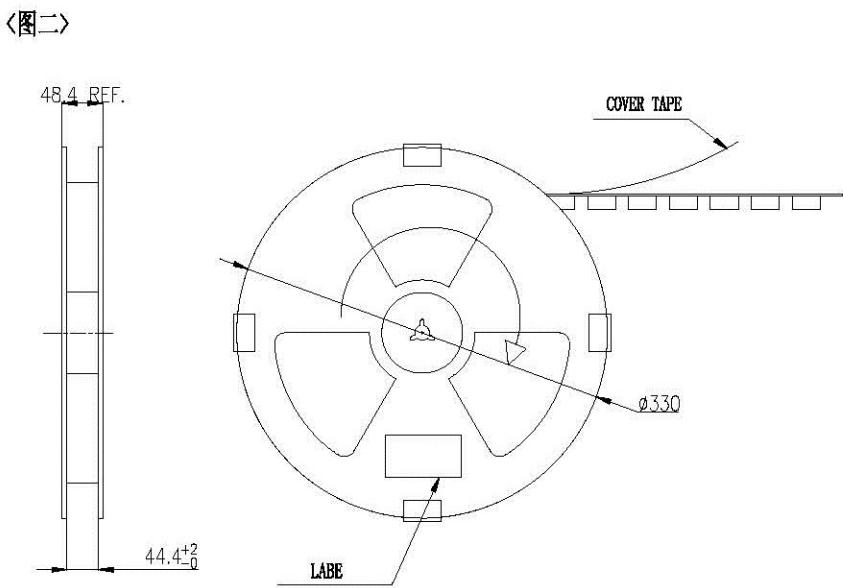
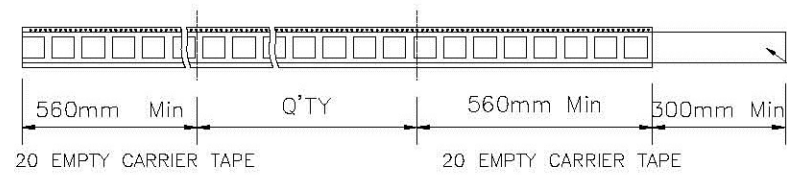
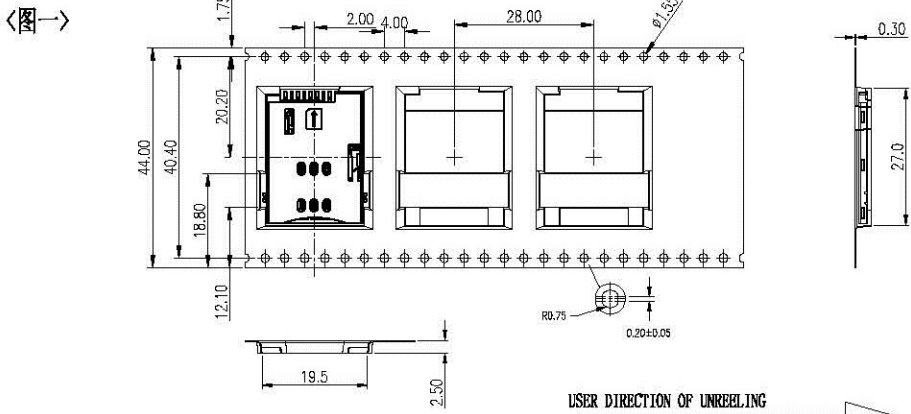
DR: Yang

TITLE: SIM card 6+2 pin push H1.8 (外壳脚5.25mm, 无定位柱)

DWG NO.: XDSM-8011-0526

SCALE	SHEET	REV.
1:1	1	A

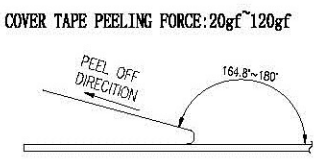
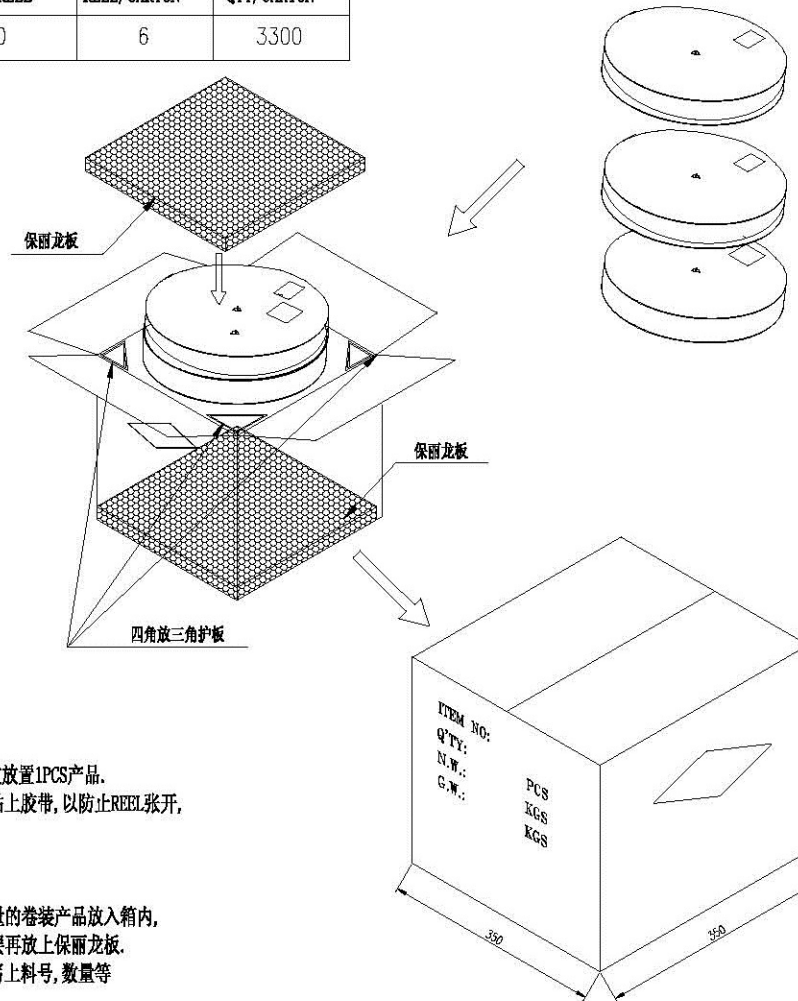
REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	2016.03.09			



<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

<图三>



- NOTE:
- 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
 - 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
 - 包装数量见如<TABLE 1>示
 - 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
 - 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

MILLIMETERS	INCH	UNITS	<h2 style="text-align: center;">深圳市连欣科技有限公司</h2>												
X° ± 2'	X° ± 2'	MM													
.X ± 0.30	.XX ± 0.012	MAT'L													
.XX ± 0.20	.XXX ± 0.008	SEE NOTES													
.XXX ± 0.10	.XXXX ± 0.004	FINISH													
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF Jin Bi Lai Electronics Group COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF Jin Bi Lai Electronics Group IS PROHIBITED.			SEE NOTES	SEE NOTES	SEE NOTES	QTY	SEE NOTES	PART NUMBER:	10201***2	TITLE:	SIM PUSH 6+2PIN H1.8 包装规范				
								APPD:	Sean	DWG NO.:					
								CHKD:							
								DR:	Yang						
										SCALE	1:1	SHEET	1	REV.	A

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